

# Surface Mounted Power Resistor Thick Film Technology


**RoHS**  
COMPLIANT

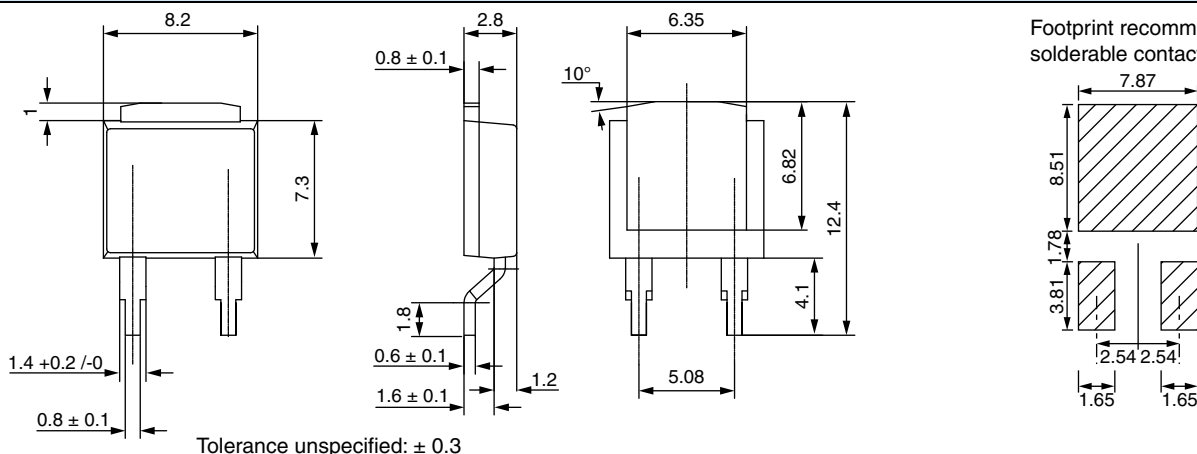
## FEATURES

- AEC-Q200 qualified
- 25 W at 25 °C case temperature
- Surface mounted resistor - TO-252 (DPAK) style package
- Wide resistance range: 0.016 Ω to 700 kΩ
- Non inductive
- Resistor isolated from metal tab
- Solder reflow secure at 270 °C / 10 s, MSL = 1
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

## LINKS TO ADDITIONAL RESOURCES



## DIMENSIONS in millimeters



## Notes

- For the assembly, we recommend the lead (Pb)-free thermal profile as per J-STD-020C
- Power dissipation is 3.2 W at an ambient temperature of 25 °C when mounted on a double sided copper board using FR4 HTG, 70 μm of copper, 39 mm x 30 mm x 1.6 mm, with thermal vias
- For other information about dissipation, see the Application Note 52027: "Thermal Management on SMD Thick Film Resistors (D2TO20, D2TO35, DT025)"

## STANDARD ELECTRICAL SPECIFICATIONS

MODEL	SIZE	RESISTANCE RANGE Ω	RATED POWER $P_{25\text{ }^{\circ}\text{C}}$ W	LIMITING ELEMENT VOLTAGE $U_L$ V	TOLERANCE ± %	TEMPERATURE COEFFICIENT ± ppm/°C	CRITICAL RESISTANCE Ω
DT025	TO-252 (DPAK)	0.016 to 700K	25	500	1, 2, 5, 10	150	10K

## MECHANICAL SPECIFICATIONS

Mechanical Protection	Molded
Resistive Element	Thick film
Substrate	Alumina
Connections	Tinned copper, Ni under layer
Weight	2 g max.

## ENVIRONMENTAL SPECIFICATIONS

Temperature Range	-55 °C to +150 °C
Climatic Category	55 / 150 / 56
Flammability	IEC 60695-11-5 Application time: $t_a = 10$ s Burning duration: $t_b < 30$ s

## ELECTRICAL SPECIFICATIONS

Tolerances	From 0.016 Ω to 0.047 Ω: ± 5 % and ± 10 % > 0.047 Ω to 0.1 Ω: ± 2 % to ± 10 % ≥ 0.11 Ω: ± 1 % to ± 10 %
Power Rating and Thermal Resistance	25 W at +25 °C case temperature $R_{TH(j-c)}$ : 5 °C/W
Temperature Coefficient	See Special Feature table ± 150 ppm/°C
Dielectric Strength	1500 $V_{RMS}$ - 1 min - 15 mA max. (between terminals and board)
Insulation Resistance	≥ 10 <sup>4</sup> MΩ
Inductance	≤ 0.1 μH

**DIMENSIONS**

Standard Package	TO-252 style (DPAK)
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**SPECIAL FEATURES**

Resistance Values	$\geq 0.016$	$\geq 0.1$	$\geq 0.5$
Requirement Temperature Coefficient (TCR) (-55 °C +150 °C) IEC 60115-1	$\pm 900$ ppm/°C	$\pm 350$ ppm/°C	$\pm 150$ ppm/°C

**PERFORMANCE**

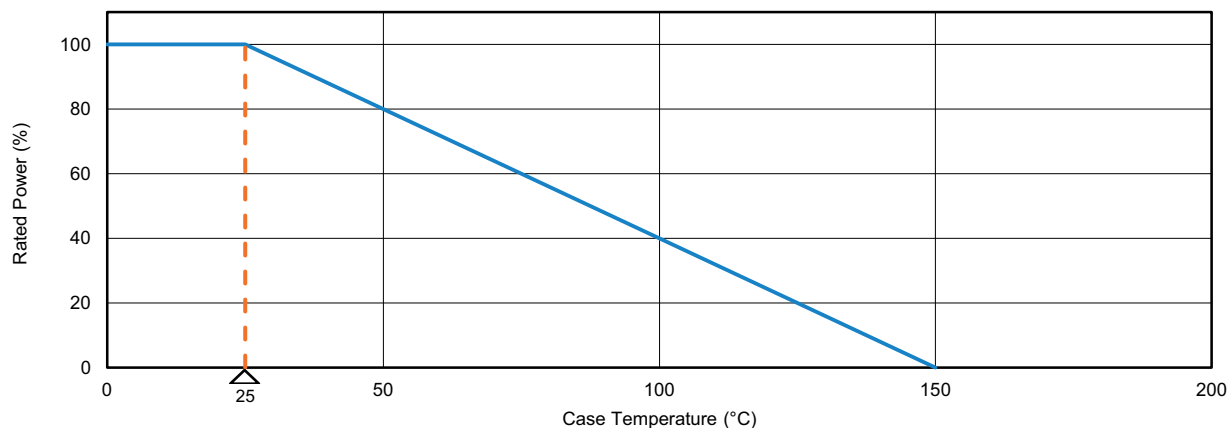
TESTS	CONDITIONS	REQUIREMENTS
Momentary Overload	IEC 60115-1 §4.13 1.6 Pr 5 s US < 1.5 UL	$\pm (0.25 \% + 0.005 \Omega)$
Load Life	IEC 60115-1 1000 h, 90/30 Pr at +25 °C	$\pm (0.5 \% + 0.005 \Omega)$
High Temperature Exposure	AEC-Q200 rev. D conditions: MIL-STD-202 method 108 1000 h, +175 °C, unpowered	$\pm (0.5 \% + 0.005 \Omega)$
Temperature Cycling	AEC-Q200 rev. D conditions: pre-conditioning 3 reflows according JESD020D JESD22 method JA-104 1000 cycles, (-55 °C to +125 °C) dwell time 15 min	$\pm (0.5 \% + 0.005 \Omega)$
Biased Humidity	AEC-Q200 rev. D conditions: MIL-STD-202 method 103 1000 h, 85 °C, 85 % RH	$\pm (0.5 \% + 0.005 \Omega)$
Operational Life	AEC-Q200 rev. D conditions: pre-conditioning 3 reflows according JESD020D MIL-STD-202 method 108 1000 h, 90/30, powered, +125 °C	$\pm (0.5 \% + 0.005 \Omega)$
ESD Human Body Model	AEC-Q200 rev. D conditions: AEC-Q200-002 25 kV <sub>AD</sub>	$\pm (0.5 \% + 0.005 \Omega)$
Vibration	AEC-Q200 rev. D conditions: MIL-STD-202 method 204 20 g's for 20 min, 12 cycles test from 10 Hz to 2000 Hz	$\pm (0.2 \% + 0.005 \Omega)$
Mechanical Shock	AEC-Q200 rev. D conditions: MIL-STD-202 method 213 100 g's, 6 ms, 3.75 m/s 3 shocks/direction	$\pm (0.2 \% + 0.005 \Omega)$
Board Flex	AEC-Q200 rev. D conditions: AEC-Q200-005 bending 2 mm, 60 s	$\pm (0.25 \% + 0.01 \Omega)$
Terminal Strength	AEC-Q200 rev. D conditions: AEC-Q200-006 1.8 kgf, 60 s	$\pm (0.25 \% + 0.01 \Omega)$

**ASSEMBLY SPECIFICATIONS**

For the assembly on board, we recommend the lead (Pb)-free thermal profile as per J-STD-020C		
TESTS	CONDITIONS	REQUIREMENTS
Resistance to Soldering Heat	AEC-Q200 rev. D MIL-STD-202 method 210 Solder bath method: 270 °C / 10 s	$\pm (0.5 \% + 0.005 \Omega)$
Moisture Sensitivity Level (MSL)	IPC / JEDEC® J-STD-020C 85 °C / 85 % RH / 168 h	Level: 1 + pass requirements of TCR overload and dielectric strength after MSL

## POWER RATING

The temperature of the case should be maintained within the limits specified.



## CHOICE OF THE BOARD

The user must choose the board according to the working conditions of the component (power, room temperature). Maximum working temperature must not exceed 150 °C. The dissipated power is simply calculated by the following ratio:

$$P = \frac{\Delta T}{R_{TH(j-c)} + R_{TH(c-h)} + R_{TH(h-a)}}^{(1)}$$

P: Expressed in W

$\Delta T$ : Difference between maximum working temperature and room temperature

$R_{TH(j-c)}$ : Thermal resistance value measured between resistive layer and outer side of the resistor. It is the thermal resistance of the component: 5 °C/W.

$R_{TH(c-h)}$ : Thermal resistance value measured between outer side of the resistor and upper side of the board. This is the thermal resistance of the solder layer.

$R_{TH(h-a)}$ : Thermal resistance of the board.

### Example:

$R_{TH(c-h)} + R_{TH(h-a)}$  for DTO25 power rating 3 W at ambient temperature +25 °C.

Thermal resistance  $R_{TH(j-c)}$ : 5 °C/W

Considering equation <sup>(1)</sup> we have:

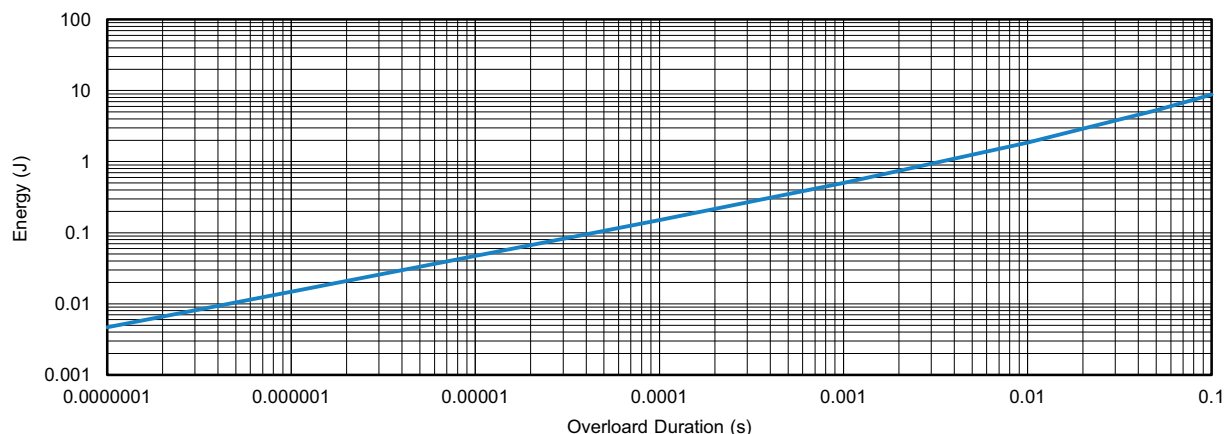
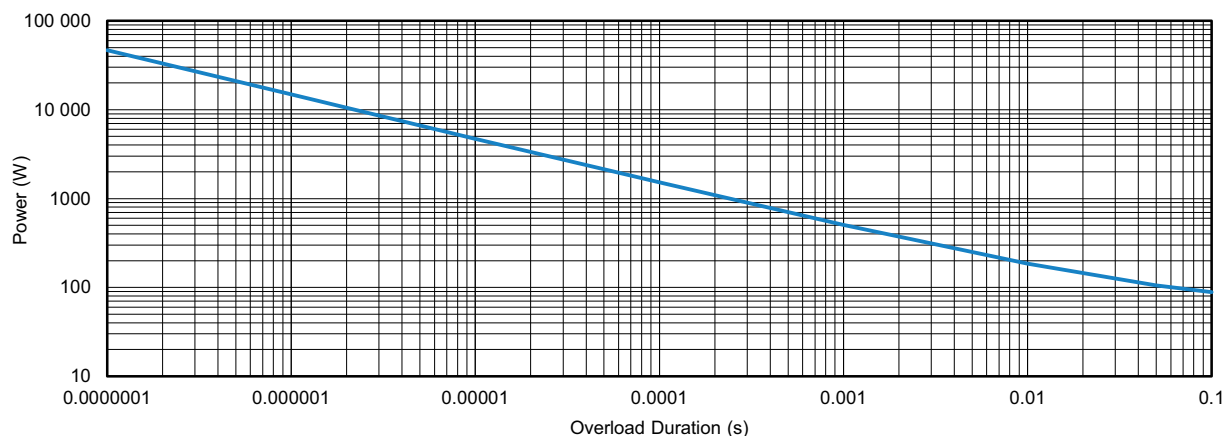
$$\Delta T = 150\text{ °C} - 25\text{ °C} = 125\text{ °C}$$

$$R_{TH(j-c)} + R_{TH(c-h)} + R_{TH(h-a)} = \Delta T / P = 125 / 3 = 41.7\text{ °C/W}$$

$$R_{TH(c-h)} + R_{TH(h-a)} = 41.7\text{ °C/W} - 5\text{ °C/W} = 36.7\text{ °C/W}$$

## ACCIDENTAL OVERLOAD

In any case the applied voltage must be lower than the maximum overload voltage of  $U_s = 750\text{ V}$ . The values indicated on the graph below are applicable to resistors onto a board.

**ENERGY CURVE** at 25 °C

**POWER CURVE** at 25 °C

**Single Pulse:**

These informations are for a single pulse on a cold resistor at 25 °C (not already used for a dissipation) and for pulses of 100 ms maximum duration.

The formula used to calculate  $E$  is:

$$E = P \times t = \frac{U^2}{R} \times t$$

with:

- $E$  (J): pulse energy
- $P$  (W): pulse power
- $t$  (s): pulse duration
- $U$  (V): pulse voltage
- $R$  ( $\Omega$ ): resistor

The energy calculated must be less than that allowed by the graph.

**Repetitive or Superimposed Pulses:**

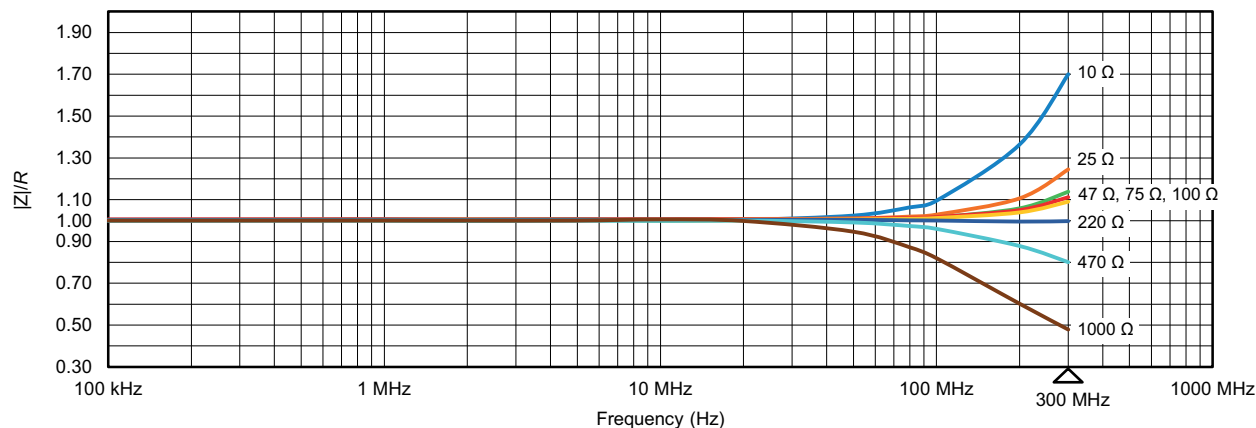
The following formula is used to calculate the "equivalent" energy of a repetitive pulse or the "equivalent energy" of a pulse on a resistor that is already dissipating power.

$$E_c = E \times \left(1 + \frac{P_a}{P_r}\right)$$

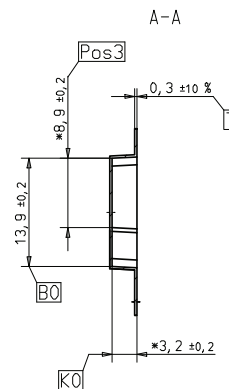
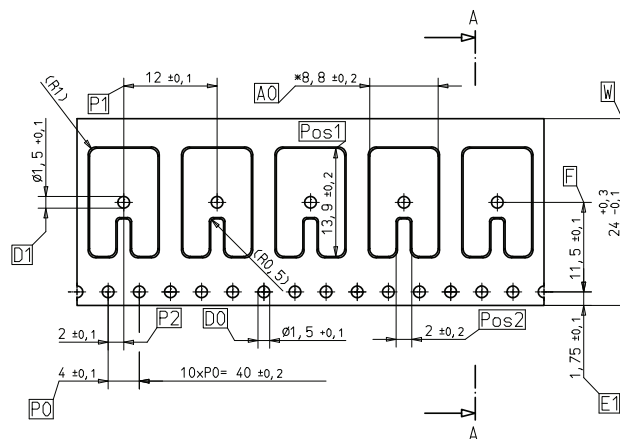
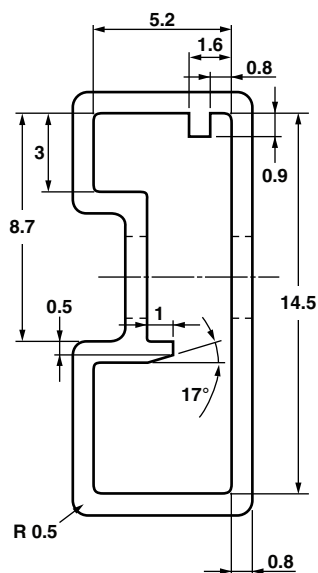
with:

- $E_c$  (J): equivalent pulse energy
- $E$  (J): known pulse energy
- $P_r$ : resistor power rating
- $P_a$ : mean power being dissipated

The energy calculated must be less than that allowed by the graph and the average power dissipated ( $P_a$ ) must not exceed the continuous power of resistor.

**IMPEDANCE CURVE** 10  $\Omega$  to 1 k $\Omega$  from 100 kHz to 300 MHz

**PACKAGING**

- Tube: max. 50 units per tube
- Reel: max. 500 units per reel


**MARKING**

Model, style, resistance value (in  $\Omega$ ), tolerance (in %), manufacturing date, Vishay Sfernice trademark.



### ORDERING INFORMATION

<b>DTO</b>	<b>025</b>	<b>C</b>	<b>100 k<math>\Omega</math></b>	<b><math>\pm 1\%</math></b>	<b>XXX</b>	<b>e3</b>
MODEL	STYLE	CONNECTIONS	RESISTANCE VALUE	TOLERANCE	CUSTOM DESIGN	LEAD (Pb)-FREE
				F = $\pm 1\%$ G = $\pm 2\%$ J = $\pm 5\%$ K = $\pm 10\%$	Optional on request: shape, etc	

### SAP PART NUMBERING GUIDELINES

<b>D</b>	<b>T</b>	<b>O</b>	<b>0</b>	<b>2</b>	<b>5</b>	<b>C</b>	<b>1</b>	<b>0</b>	<b>0</b>	<b>0</b>	<b>2</b>	<b>F</b>	<b>R</b>	<b>E</b>	<b>3</b>
GLOBAL MODEL	SIZE	LEADS	OHMIC VALUE				TOLERANCE		PACKAGING		LEAD (Pb)-FREE / PACKAGING				
<b>DTO</b>	<b>025</b>	<b>C</b> = surface mount	The first four digits are significant figures and the last digit specifies the number of zeros to follow. R designates decimal point.  <b>48R70</b> = 48.7 $\Omega$ <b>48701</b> = 48 700 $\Omega$ <b>10002</b> = 100 000 $\Omega$ <b>R0100</b> = 0.01 $\Omega$ <b>R6800</b> = 0.68 $\Omega$ <b>27000</b> = 2700 $\Omega$ = 2.7 k $\Omega$				<b>F</b> = 1 % <b>G</b> = 2 % <b>J</b> = 5 % <b>K</b> = 10 %		<b>R</b> = reel 500 pieces <b>T</b> = tube 50 pieces		<b>E3</b> = standard packaging reel 500 or tube 50 and lead (Pb)-free (pure tin) <b>15</b> = 1000 pcs. reel and lead (Pb)-free (pure tin)				



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